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IFW

PATENT  
8026-1004

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Koki HIRASAWA et al.

Conf. 2347

Application No. 09/923,394

Group 2826

Filed August 8, 2001

Examiner F. Erdem

LEAD FRAME, SEMICONDUCTOR DEVICE  
PRODUCED BY USING THE SAME AND  
METHOD OF PRODUCING THE  
SEMICONDUCTOR DEVICE

**FURTHER SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

MS AMENDMENT

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In compliance with Rules 1.97 and 1.98, and in fulfillment of the duty of disclosure under Rule 1.56, the accompanying documents, copies of which are attached to this statement, are made of record on the enclosed Form PTO-1449.

A concise explanation of the relevance of these items is that these references were cited by the German Patent Office in the corresponding German Application Serial No. 101 38 982.5-33. A copy of the German Official Action in which they were cited is attached hereto, with **an English translation also attached hereto.**

Under the provisions of 37 CFR 1.97(e), the undersigned hereby certifies that each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign Patent Office in a

counterpart foreign application not more than three months prior to the filing of this Statement.

Respectfully submitted,

YOUNG & THOMPSON



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